



M T B F (E I A J R C R - 9 1 0 2 B)

					Model	SNDPF1000
No.	P a r t s		Q' ty of Device	Failure rate [10 ⁻⁶ /H]	R e f e r e n c e	
1	IC	Linear	1	0.0240		
2	T r a n s i s t o r s	NPN/PNP	1	0.0011		
3	D i o d e s	FR	0	0.0000		
4	D i o d e s	switching	2	0.0150		
5	D i o d e s	Zener	1	0.0240		
6	Photoelectron Device	Photo-coupler	0	0.0000		
7	R e s i s t o r s	Metal Film	11	0.1760		
8	R e s i s t o r s	Carbon Film	0	0.0000		
9	R e s i s t o r s	Power Film	4	0.1640		
10	R e s i s t o r s	Temperature Fuse	2	0.1560		
11	R e s i s t o r s	variable	0	0.0000		
12	V a r i s t o r	Varistor	2	0.0460		
13	C a p a c i t o r s	Aluminum Electrolytic	5	0.0950		
14	C a p a c i t o r s	Film	9	0.0756		
15	C a p a c i t o r s	Ceramic	3	0.0780		
16	Coil	Line Filter	2	0.0009		
17	Coil	Ferrite Beads	0	0.0000		
18	Fuses		1	0.0200		
19	S w i t c h	Toggle	1	0.5000		
20	C o n n e c t o r s	Printed Crcuit Board	5	0.2600		
21	Connection	Hand Solder	9	0.0234		
22	Connection	Flow Solder	265	0.1378		
23	Connection	Screw	13	0.0130		
24	Printed Crcuit Board	Through Hole	1	0.0450		
25	P S 1		1	2.8992		
Total Failure Rate [10 ⁻⁶ /H]				4.7540		

M T B F	[H]	210,000
Ambient Temperature	[℃]	-
Load Factor	[%]	-